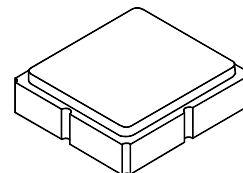


- **Low-loss UHF SAW Filter**
- **Single-ended Input, Balanced Output**
- **3.0 x 3.0 mm Surface-mount Package**
- **Complies with Directive 2002/95/EC (RoHS)**



SF1219E

**2338.75 MHz
SAW Filter**



SM3030-8

Maximum Rating

Rating	Value	Units
Input Power Level	+15	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-40 to +105	°C
Component Storage Temperature Range	-40 to +105	°C
Tape and Reel Storage Temperature Range	-40 to +85	°C
Solder Reflow Temperature, 10 seconds/5 cycles maximum	260	°C

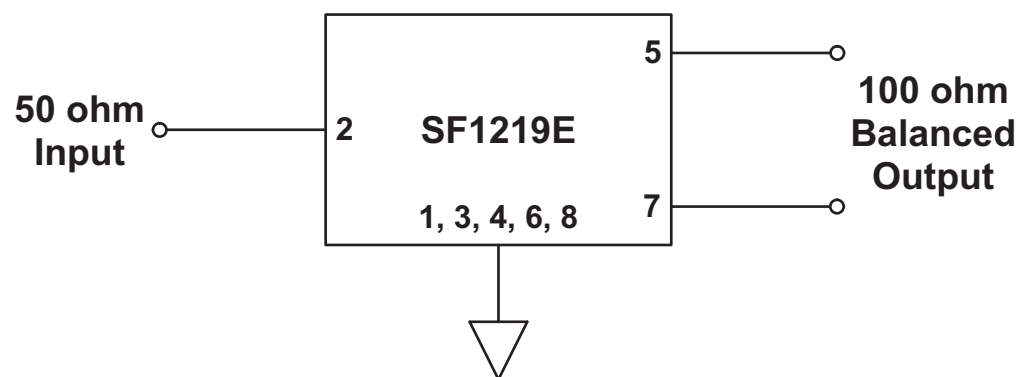
Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f _C			2338.75		MHz
Maximum Insertion Loss, 2332.5 to 2345 MHz	IL _{MAX}			2.8	4.5	dB
Amplitude Ripple, 2332.5 to 2345 MHz				0.2	1.4	dB _{p.p}
Group Delay Ripple, 2332.5 to 2345 MHz				4	12	ns _{p.p}
Input Return Loss, 2332.5 to 2345 MHz			6.5	13		dB
Output Return Loss, 2332.5 to 2345 MHz			6.5	10		dB
Attenuation, 0 dB Reference:						
88 to 108 MHz			60	80		dB
880 to 960 MHz			55	69		
1710 to 1910 MHz			40	50		
2305 MHz				22		
2310 MHz				17		
2315 MHz				11		
2320 MHz				7		
2450 MHz			30	44		
3060 MHz			35	58		
Single-ended Source Impedance				50		ohm
Balanced Load Impedance				100		
Case Style						
Lid Symbolization, Y=year, WW=week, S=shift, dot=pin 1 indicator			SM3030-8 3.0 x 3.0 mm Nominal Footprint			
Standard Reel Quantity			953, YWWS			
Reel Size 7 inch			500 Pieces/Reel			
Reel Size 13 inch			3000 Pieces/Reel			

NOTES:

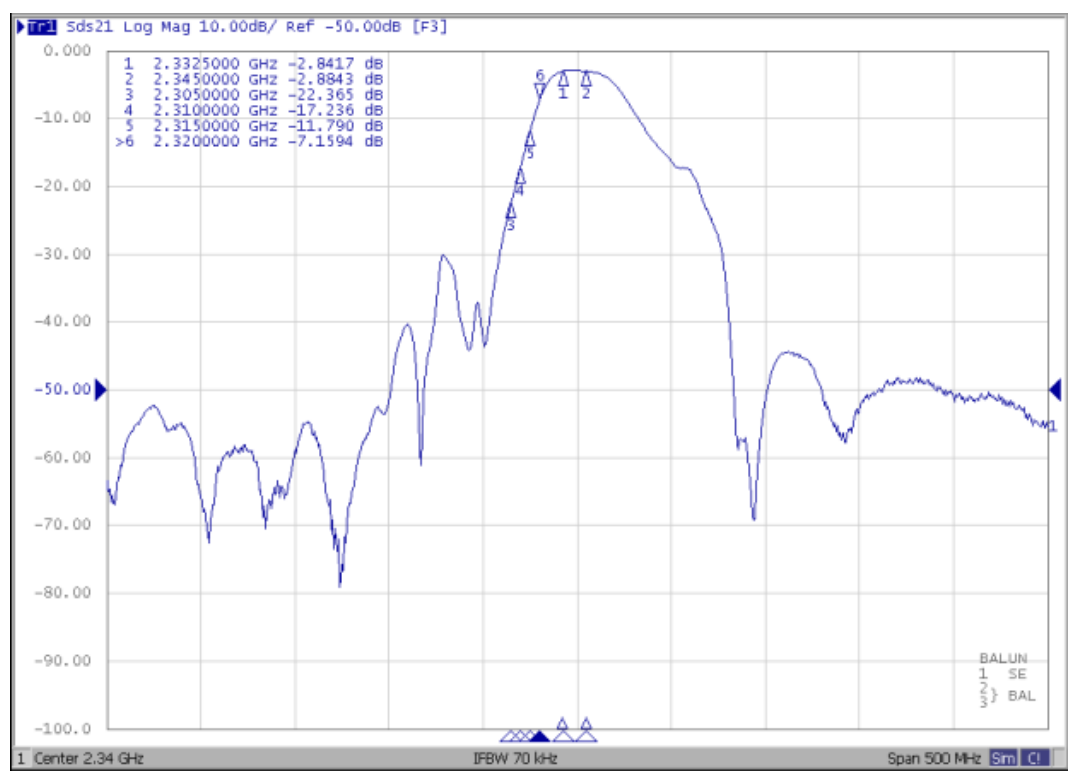
1. US and international patents may apply.
2. Murata, stylized Murata logo, and Murata N.A., Inc. are registered trademarks of Murata Manufacturing Co., Ltd.
3. Electrostatic Sensitive Device. Observe precautions for handling.

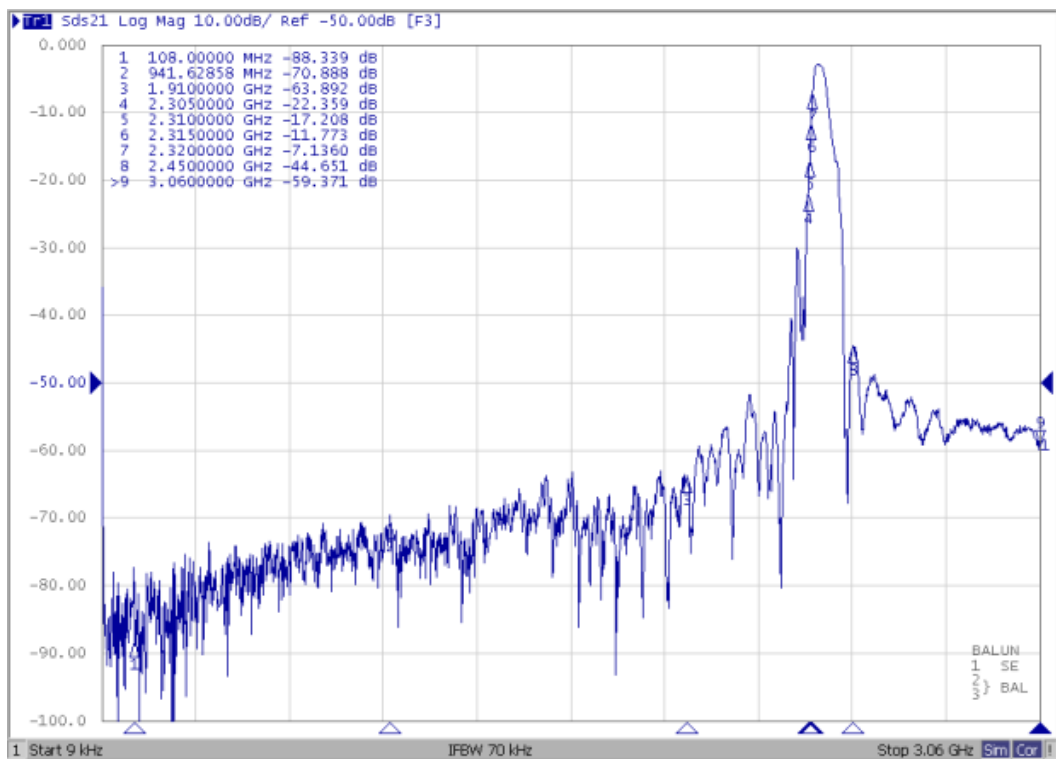
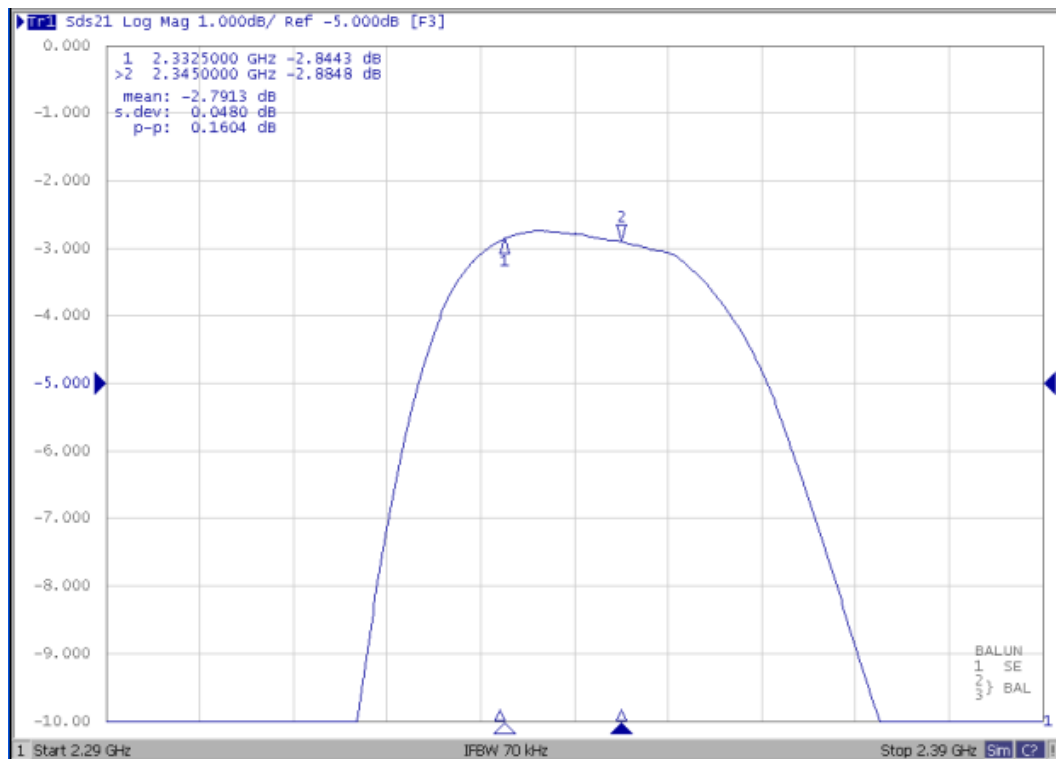


Test Circuit

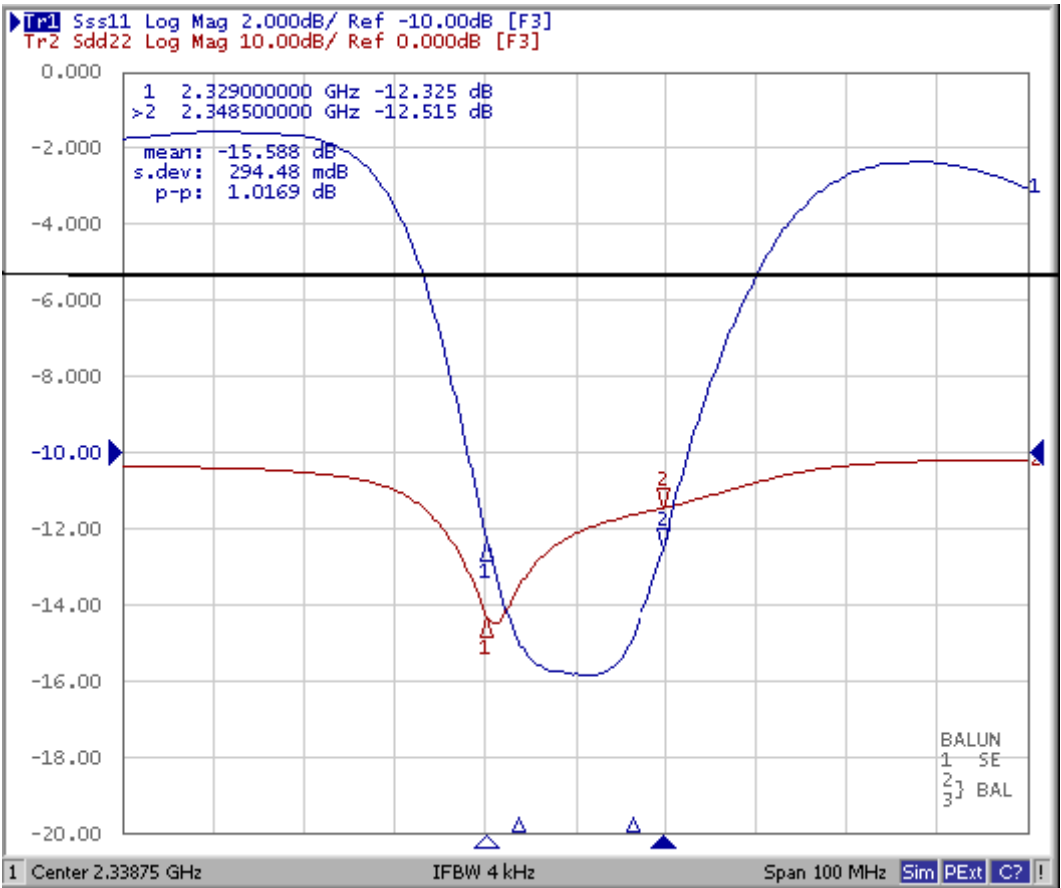


Filter Response Plots



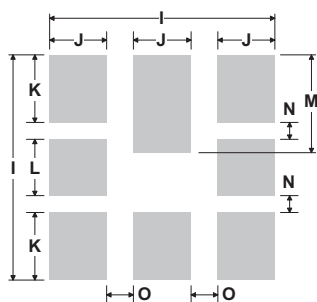
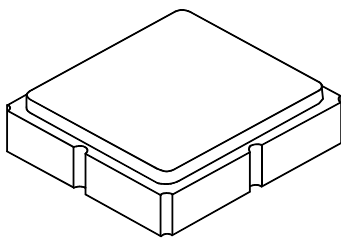


Filter Return Loss Plot



8-Terminal Ceramic Surface-Mount Case

3.0 x 3.0 mm Nominal Footprint



PCB Footprint Top View

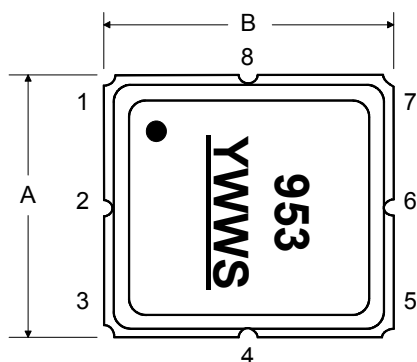
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	-	-	1.10	-	-	0.043
D	0.79	0.92	1.05	0.031	0.036	0.041
E	0.62	0.75	0.88	0.024	0.029	0.034
F	0.47	0.60	0.73	0.018	0.024	0.029
G	0.47	0.60	0.73	0.018	0.024	0.029
H	1.07	1.20	1.33	0.042	0.047	0.052
I		3.19			0.126	
J		0.81			0.032	
K		0.96			0.038	
L		0.81			0.032	
M		1.39			0.055	
N		0.23			0.009	
O		0.38			0.015	

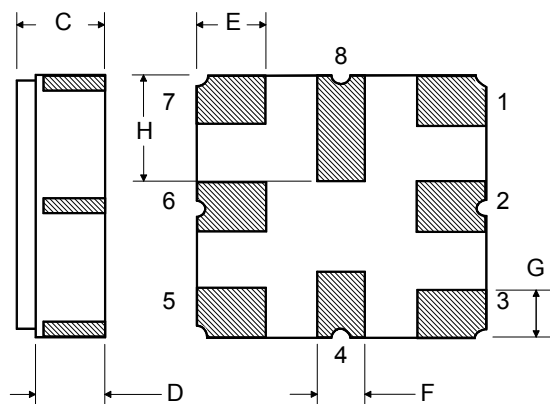
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic
Pb Free	

TOP VIEW



BOTTOM VIEW



Technical drawing of a circular component. The main view shows a large circle with a central hole. The hole is defined by a dashed circle with a diameter of $\phi 100$ REF. and a solid circle with a diameter of $\phi 330$ REF. The hole is centered on a vertical dashed line. A dimension of 16.8 ± 0.1 is shown for the distance from the top edge to the center of the hole. A dimension of 24.2 ± 0.1 is shown for the distance from the bottom edge to the center of the hole. A detail view of the hole is shown at the bottom right, labeled "DETAIL 'A'". This detail shows a cross-section of the hole with a diameter of $\phi 130.05 \pm 0.2$ and a depth of 20 ± 0.5 . The detail also shows a chamfer with a diameter of $\phi 20.2 \text{ min}$. A leader line points from the text "See DETAIL 'A'" to the detail view.

Carrier Tape Dimensions	
Ao	3.35 mm
Bo	3.35 mm
Ko	1.4 mm
Pitch	8.0 mm
W	12.0 mm

[illegible]